



<b>Title of Change:</b>	Copper wire conversion and mold compound change for LA72900VA		
<b>Proposed first ship date:</b>	15 January 2016		
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <lkuo.Osawa@onsemi.com><Hidekazu.Inoue@onsemi.com> <Hiroshi.Kojima@onsemi.com> <Takeshi2.Hoshino@onsemi.com><Kazumi.Onda@onsemi.com><Kenya.liguchi@onsemi.com>		
<b>Samples:</b>	Samples should be available after completion of qualification. Contact your local ON Semiconductor Sales Office or <Jun.Hasunuma@onsemi.com>		
<b>Type of notification:</b>	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.		
<b>Change Part Identification:</b>	Affected products will be identified with date code.		
<b>Change category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____		
<b>Change Sub-Category(s):</b>	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____		
<b>Sites Affected:</b>	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Tarlac City, Philippines <input type="checkbox"/> External Foundry/Subcon site(s)		
<b>Description and Purpose:</b>	This is an Initial Process Change Notification for below contents. 1) Gold wire connecting chip and Lead will be changed to Copper wire. 2) Mold resin will be changed to suitable for Copper wire.  There is no change of the electrical characteristic specifications with this changing.		
<b>Qualification Plan:</b>	Estimated date for qualification completion: 31 July 2015 Package name :SSOP024 (V4B90)		
	Test Items	Test Condition	Test Time
	High Temperature Operating Life	Tj=Tjmax, Vcc=Operatingmax	1000hrs
	Temperature Humidity Bias *	Ta=85degC,RH=85%, Vcc=Recommended T	1000hrs
	Temperature Cycle *	Ta=-65degC(30min) ↔ Ta=150degC (30min)	100cycles
	Pressure Cooker *	Ta=121degC,RH=100% ,205kPa	50hrs
	High Temperature Storage	Ta=150degC	1000hrs
	Resistance to Soldering heat (Reflow Soldering )	255degC,10s (Peak260degC)	2times
<b>Notes:</b>	The test items with * mark are put into operation after the reflow soldering (at 255degC for 10seconds) -> SMD Temperature Humidity Bias Test: PD>=0.1W -> Intermittent power application consists of 1h ON and 3h OFF.		
<b>Judgment Criteria :</b>	Judgment Criteria are due to the limits of the electrical characteristics in the detail specification		



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**List of affected Standard Parts:**

Part Number	Qualification Vehicle
LA72900VA-TLM-E	LA72900VA-TLM-E